

# UltraVim 4D-35mm Vision Module

The UltraVim 4D module can inspect a variety of leaded device packages including QFP, TSOP and SOIC packages in three dimensions. Standard device file libraries provide for easy setup and training. The standstill time is less than 20 milliseconds and there is no need to plunge the device.



## Features

- Fast Standstill Times
- Standard Part Library
- Windows XPe or 7 Interface
- Ethernet or RS232 Host Protocol

## Options

- 2D Inspection Software
- Digital I/O Protocol

## Standard Measurements

- Coplanarity, Pitch, Bent Lead, Tip Error
- Max Package Size.....32.000 mm
- Min Lead Width.....0.220 mm
- Min Lead Pitch.....0.500 mm
- Min BGA Diameter.....0.250 mm

## Technical Data

- Camera Pixels.....1288 x 964
- Field of View.....35.000 mm
- MM per Pixel.....0.035 mm
- Module Width.....136.525 mm
- Module Length.....136.525 mm
- Module Height.....327.025 mm

